



Form 1449 (Modified)	Atty Docket No. NSC1P300/P05882	Application No.: 10/824,903
<b>Information Disclosure Statement By Applicant</b>	Applicant: Kelkar	
(Use Several Sheets if Necessary)	Filing Date 04/14/2004	Group 2891

### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
DAZ	A1	2005-0516331	07/21/05	Akram			03/10/05
	A2	2003-0218258	11/27/03	Charles et al.			05/20/03
	A3	2005-0212142	09/29/05	Miyazaki et al.			04/28/05
	A4	2003-0193096	10/16/03	Tao et al.			01/28/03
	A5	2002-0171152	11/21/02	Miyazaki			05/20/02
	A6	2003-0169064	09/11/03	Pirkle et al.			01/15/03
	A7	2003-0129789	07/10/03	Smith et al.			01/29/03
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	A21	5,329,423	07/12/94	Scholz			04/13/93
	A22	5,736,456	04/07/98	Akram			07/17/96
	A23	5,767,010	06/16/98	Mis, et al.			11/05/96
	A24	5,773,359	06/30/98	Mitchell, et al.			12/26/95
	A25	5,937,320	08/10/95	Andricacos, et al.			04/08/98
	A26	5,977,632	11/02/99	Beddingfield			02/02/98
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Examiner /David Zarneke/				Date Considered 09/22/2006			

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Information Disclosure  
Statement By Applicant

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2891

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Examiner	/David Zarneke/			Date Considered	09/22/2006		

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04/14/2004	2891	

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**Other Documents**

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DAZ	C1	Kulicke & Soffa, Flip Chip Division, Polymer Collar™ Wafer Level Package; "Achieve Maximum Reliability for Wafer Level Packages!", December 7, 2001, <a href="http://www.kns.com">www.kns.com</a>
	C2	Kulicke & Soffa, Flip Chip Division, Polymer Collar™ Wafer Level Package, "See the Polymer Collar™ WLP Difference!", December 7, 2001, <a href="http://www.kns.com">www.kns.com</a> .
	C3	Lau et al., "Chip Scale Package: Design, Materials, Process, Reliability, and Applications," February 28, 1999, McGraw-Hill Professional Publishing; Chapter 1, pages 1-41.
	C4	Rao R. Tummala, "Fundamentals of Microsystem Packaging," May 8, 2001, McGraw-Hill Professional Publishing; Chapters 2, 10 and 17.
	C5	"Polymer Collar WLP™, Wafer Level Package Family", © 2002, downloaded from <a href="http://www.kns.com/prodserv/PDFS/FCD/polymer_collar.pdf">www.kns.com/prodserv/PDFS/FCD/polymer_collar.pdf</a> , 2 pages.
	C6	"Presenting Polymer Collar WLP™ – A New Wafer Level Package for Improved Solder Joint Reliability", © 2002, downloaded from <a href="http://www.kns.com/prodserv/flipchip/pdf/PC_ad.pdf">www.kns.com/prodserv/flipchip/pdf/PC_ad.pdf</a> , 1 page.
	C7	Barrett et al., Kulicke & Soffa, "Polymer Collar WLP™ – A New Wafer Level Package for Improved Solder Joint Reliability", © 2002, downloaded from <a href="http://www.kns.com/resources/articles/PolymerCollar.pdf">www.kns.com/resources/articles/PolymerCollar.pdf</a> , 9 pages.
	C8	Bogatin, Eric, "All Dressed Up and Nowhere to Go"; Semiconductor International, May 1, 2002, downloaded December 23, 2003, from <a href="http://www.reed-electronics.com/semiconductor/index.asp?layout=article@articleid=CA213812@rid=0&amp;rme=0&amp;cfd=1">www.reed-electronics.com/semiconductor/index.asp?layout=article@articleid=CA213812@rid=0&amp;rme=0&amp;cfd=1</a> , 2 pages.
DAZ	C9	Nguyen et al., "Effect of Underfill Fillet Configuration on Flip Chip Package Reliability", SEMI® Technology Symposium: International Electronics Manufacturing Technology (IEMT) Symposium, SEMICON® West 2002.
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	Date Considered	09/22/2006

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**Other Documents**

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DAZ	C10	U.S. Patent Application 10/080,913, filed February 21, 2002.
✓	C11	U.S. Patent Application 10/224,291, filed August 19, 2002.
DAZ	C12	U.S. Patent Application 10/707,208, filed November 26, 2003.
Examiner DAZ		Date Considered /David Zarneke/

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